DSA3G01

Silicon PNP epitaxial planar type

For high-frequency amplification DSA9G01 in SSSMini3 type package

■ Features

- High transition frequency f_T
- Halogen-free / RoHS compliant
 (EU RoHS / UL-94 V-0 / MSL: Level 1 compliant)

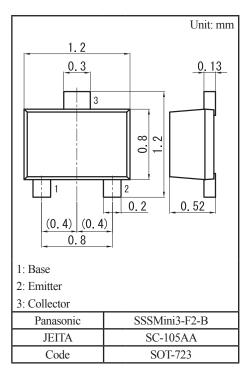
■ Marking Symbol: A4

Packaging

DSA3G0100L Embossed type (Thermo-compression sealing): 10000 pcs / reel (standard)

■ Absolute Maximum Ratings $T_a = 25$ °C

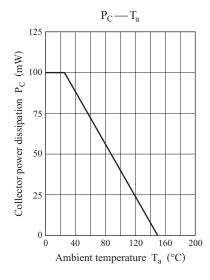
Parameter	Symbol	Rating	Unit
Collector-base voltage (Emitter open)	V _{CBO}	-30	V
Collector-emitter voltage (Base open)	V _{CEO}	-20	V
Emitter-base voltage (Collector open)	V_{EBO}	-5	V
Collector current	I_{C}	-30	mA
Collector power dissipation	P _C	P _C 100	
Junction temperature	T_j	150	°C
Operating ambient temperature	T _{opr}	-40 to +85	°C
Storage temperature	T _{stg}	-55 to +150	°C

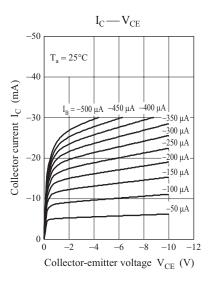


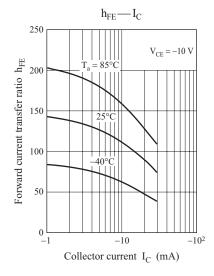
■ Electrical Characteristics $T_a = 25$ °C±3°C

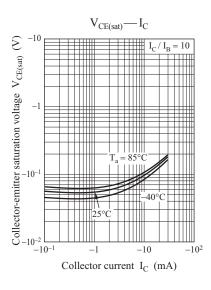
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Base-emitter voltage	V_{BE}	$V_{CE} = -10 \text{ V}, I_{C} = -1 \text{ mA}$		-0.7		V
Collector-base cutoff current (Emitter open)	I_{CBO}	$V_{\rm CB} = -10 \text{ V}, I_{\rm E} = 0$			-0.1	μА
Collector-emitter cutoff current (Base open)	I _{CEO}	$V_{CE} = -20 \text{ V}, I_{B} = 0$			-100	μА
Emitter-base cutoff current (Collector open)	I_{EBO}	$V_{EB} = -5 \text{ V}, I_{C} = 0$			-10	μА
Forward current transfer ratio	h _{FE}	$V_{CE} = -10 \text{ V}, I_{C} = -1 \text{ mA}$	70		220	_
Collector-emitter saturation voltage	V _{CE(sat)}	$I_C = -10 \text{ mA}, I_B = -1 \text{ mA}$		-0.1		V
Transition frequency	f_T	$V_{CE} = -10 \text{ V}, I_{C} = -1 \text{ mA}$	150	300		MHz
Reverse transfer capacitance (Common emitter)	C _{re}	$V_{CE} = -10 \text{ V}, I_{C} = -1 \text{ mA}, f = 10.7 \text{ MHz}$		1.0		pF
Noise figure	NF	$V_{CE} = -10 \text{ V}, I_{C} = -1 \text{ mA}, f = 5 \text{ MHz}$		2.8		dB
Reverse transfer impedance	Z _{rb}	$V_{CE} = -10 \text{ V}, I_{C} = -1 \text{ mA}, f = 2 \text{ MHz}$		22		Ω

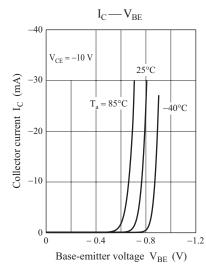
Note) Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

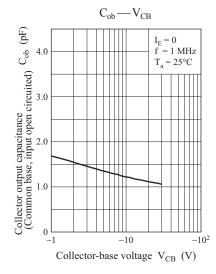


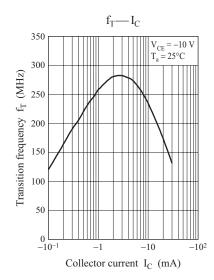








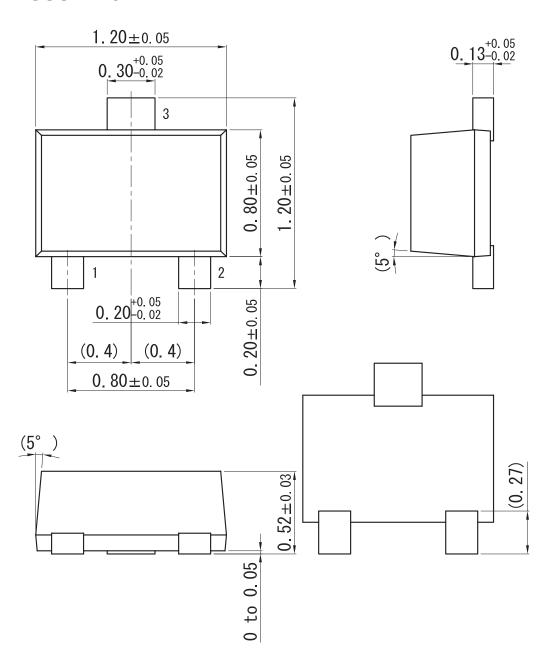




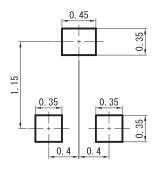
Ver. CED 2

SSSMini3-F2-B

Unit: mm



■ Land Pattern (Reference) (Unit: mm)



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